onsemi

Linear Voltage Regulator -Low Dropout, Ultra-Low Iq, Wide Input Voltage

50 mA

NCV8715

The NCV8715 is 50 mA LDO Linear Voltage Regulator. It is a very stable and accurate device with ultra-low ground current consumption (4.7 μ A over the full output load range) and a wide input voltage range (up to 24 V). The regulator incorporates several protection features such as Thermal Shutdown and Current Limiting.

Features

- Operating Input Voltage Range: 2.5 V to 24 V
- Fixed Voltage Options Available: 1.2 V to 5.0 V
- Ultra Low Quiescent Current: Max. 5.8 µA Over Full Load and Temperature
- ±2% Accuracy Over Full Load, Line and Temperature Variations
- PSRR: 52 dB at 100 kHz
- Noise: 190 μV_{RMS} from 200 Hz to 100 kHz
- Thermal Shutdown and Current Limit protection
- Available in XDFN6 1.5 x 1.5 mm and SC-70 (SC-88A) Package
- NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable; Device Temperature Grade 1: -40°C to +125°C Ambient Operating Temperature Range
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications

- Infotainment, Audio
- Communication Systems
- Safety Systems

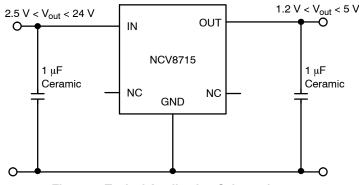
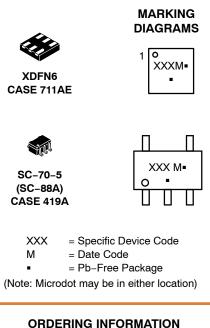
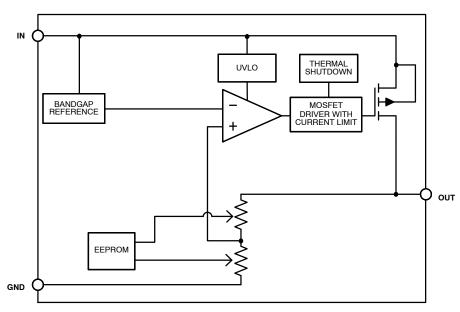


Figure 1. Typical Application Schematic



See detailed ordering, marking and shipping information on page 19 of this data sheet.





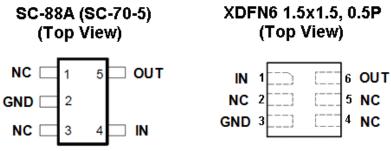


Figure 3. Pin Description

PIN FUNCTION DESCRIPTION

| Pin | Pin No. | | |
|-------|---------|----------|---|
| SC-70 | XDFN6 | Pin Name | Description |
| 5 | 6 | OUT | Regulated output voltage pin. A small 0.47 μF ceramic capacitor is needed from this pin to ground to assure stability. |
| 1 | 2 | N/C | No connection. This pin can be tied to ground to improve thermal dissipation or left disconnected. |
| 2 | 3 | GND | Power supply ground. |
| 3 | 4 | N/C | No connection. This pin can be tied to ground to improve thermal dissipation or left disconnected. |
| - | 5 | N/C | No connection. This pin can be tied to ground to improve thermal dissipation or left disconnected. |
| 4 | 1 | IN | Input pin. A small capacitor is needed from this pin to ground to assure stability. |

ABSOLUTE MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|---|---------------------|------------|------|
| Input Voltage (Note 1) | V _{IN} | -0.3 to 24 | V |
| Output Voltage | V _{OUT} | –0.3 to 6 | V |
| Output Short Circuit Duration | t _{SC} | Indefinite | s |
| Maximum Junction Temperature | T _{J(MAX)} | 150 | °C |
| Operating Ambient Temperature Range | T _A | -40 to 125 | °C |
| Storage Temperature Range | T _{STG} | –55 to 150 | °C |
| Moisture Sensitivity Level | MSL | MSL1 | - |
| ESD Capability, Human Body Model (Note 2) | ESD _{HBM} | 2000 | V |
| ESD Capability, Machine Model (Note 2) | ESD _{MM} | 200 | V |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Refer to ELECTRICAL CHARACTERISTICS and APPLICATION INFORMATION for Safe Operating Area.

2. This device series incorporates ESD protection and is tested by the following methods:

- ESD Human Body Model tested per EIA/JESD22-A114
- ESD Machine Model tested per EIA/JESD22–A115

ESD Charged Device Model tested per EIA/JESD22-C101E

Latch up Current Maximum Rating tested per JEDEC standard: JESD78.

THERMAL CHARACTERISTICS

| Rating | Symbol | Value | Unit |
|---|---------------|-------|------|
| Thermal Characteristics, SC-70 (Note 3) Thermal Resistance, Junction-to-Air (Note 4) | $R_{	hetaJA}$ | 390 | °C/W |
| Thermal Characteristics, XDFN6 (Note 3) Thermal Resistance, Junction-to-Air (Note 4) | $R_{	hetaJA}$ | 260 | °C/W |

3. Refer to ELECTRICAL CHARACTERISTICS and APPLICATION INFORMATION for Safe Operating Area.

4. As measured using a copper heat spreading area of 650 mm², 1 oz copper thickness.

RECOMMENDED OPERATING CONDITIONS

| Parameter | Symbol | Min | Max | Unit |
|----------------------|-----------------|-----|-----|------|
| Input Voltage | V _{IN} | 2.5 | 24 | V |
| Junction Temperature | TJ | -40 | 125 | °C |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

ELECTRICAL CHARACTERISTICS – Voltage Version 1.2 V

 $-40^{\circ}C \le T_J \le 125^{\circ}C$; $V_{IN} = 2.5$ V; $I_{OUT} = 1$ mA, $C_{IN} = C_{OUT} = 1.0 \ \mu$ F, unless otherwise noted. Typical values are at $T_J = +25^{\circ}C$. (Note 7)

| | | | | | | , |
|---------------------------------------|---|---------------------|-------|-----|-------|-------------------|
| Parameter | Test Conditions | Symbol | Min | Тур | Max | Unit |
| Operating Input Voltage | I _{OUT} ≤ 10 mA | V _{IN} | 2.5 | | 24 | V |
| | 10 mA< I _{OUT} < 50 mA | 1 | 3.0 | | 24 | |
| Output Voltage Accuracy | 3.0 V < V _{IN} < 24 V, 0 mA < I _{OUT} < 50 mA | V _{OUT} | 1.164 | 1.2 | 1.236 | V |
| Line Regulation | $2.5 \text{ V} \leq \text{V}_{IN} \leq 24 \text{ V}, \text{ I}_{OUT} = 1 \text{ mA}$ | Reg _{LINE} | | 2 | 10 | mV |
| Load Regulation | I _{OUT} = 0 mA to 50 mA | Reg _{LOAD} | | 5 | 10 | mV |
| Dropout Voltage (Note 5) | | V _{DO} | | | - | mV |
| Maximum Output Current | (Note 8) | I _{OUT} | 100 | | 200 | mA |
| | 0 < I _{OUT} < 50 mA, V _{IN} = 24 V | I _{GND} | | 3.4 | 5.8 | |
| Power Supply Rejection Ratio | $ \begin{array}{c} V_{IN} = 3.0 \text{ V}, V_{OUT} = 1.2 \text{ V} \\ V_{PP} = 200 \text{ mV modulation} \\ I_{OUT} = 1 \text{ mA}, C_{OUT} = 10 \mu F \end{array} \right f = 100 \text{ kHz} $ | PSRR | | 60 | | dB |
| Output Noise Voltage | V_{OUT} = 1.2 V, I_{OUT} = 50 mA f = 200 Hz to 100 kHz, C_{OUT} = 10 μF | V _N | | 65 | | μV _{rms} |
| Thermal Shutdown Temperature (Note 6) | Temperature increasing from $T_J = +25^{\circ}C$ | T _{SD} | | 170 | | °C |
| Thermal Shutdown Hysteresis (Note 6) | Temperature falling from T _{SD} | T _{SDH} | - | 15 | - | °C |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 5. Not Characterized at $V_{IN} = 3.0 \text{ V}$, $V_{OUT} = 1.2 \text{ V}$, $I_{OUT} = 50 \text{ mA}$. 6. Guaranteed by design and characterization.

7. Performance guaranteed over the indicated operating temperature range by design and/or characterization production tested at $T_J = T_A = 25^{\circ}$ C. Low duty cycle pulse techniques are used during testing to maintain the junction temperature as close to ambient as possible.

8. Respect SOA.

ELECTRICAL CHARACTERISTICS – Voltage Version 1.5 V

 $-40^{\circ}C \le T_J \le 125^{\circ}C$; $V_{IN} = 2.5 V$; $I_{OUT} = 1 \text{ mA}$, $C_{IN} = C_{OUT} = 1.0 \mu$ F, unless otherwise noted. Typical values are at $T_J = +25^{\circ}C$. (Note 11)

| Parameter | Test Conditions | Syn | nbol | Min | Тур | Max | Unit |
|---|---|-------------------|------|-------|-----|-------|-------------------|
| Operating Input Voltage | l _{OUT} ≤ 10 mA | V | N | 2.5 | | 24 | V |
| | 10 mA < I _{OUT} < 50 mA | | | 3.0 | | 24 | |
| Output Voltage Accuracy | 3.0 V < VIN < 24 V, 0 < I _{OUT} < 50 m. | v Vo | UT | 1.455 | 1.5 | 1.545 | V |
| Line Regulation | Vout + 1 V \leq VIN \leq 24 V, I _{OUT} = 1 m | A Reg | LINE | | 2 | 10 | mV |
| Load Regulation | I _{OUT} = 0 mA to 50 mA | Reg | OAD | | 5 | 10 | mV |
| Dropout Voltage (Note 9) | | V | 00 | | | - | mV |
| Maximum Output Current | (Note 12) | ۱ ₀ | UT | 100 | | 200 | mA |
| Ground Current | 0 < I _{OUT} < 50 mA, V _{IN} = 24 V | I _{GI} | ND | | 3.4 | 5.8 | μA |
| Power Supply Rejection Ratio | $ \begin{array}{c} V_{IN} = 3.0 \ V, \ V_{OUT} = 1.5 \ V \\ V_{PP} = 200 \ mV \ modulation \\ I_{OUT} = 1 \ mA, \ C_{OUT} = 10 \ \mu F \end{array} f = 100 \label{eq:VP} $ | (Hz PS | RR | | 56 | | dB |
| Output Noise Voltage | V_{OUT} = 1.5 V, I_{OUT} = 50 mA f = 200 Hz to 100 kHz, C_{OUT} = 10 μ | - V | N | | 75 | | μV _{rms} |
| Thermal Shutdown Temperature (Note 10) | Temperature increasing from $T_J = +25$ | °C T _s | SD | | 170 | | °C |
| Thermal Shutdown Hysteresis (Note 10) | Temperature falling from T _{SD} | Τ _S | DH | - | 15 | - | °C |

9. Not Characterized at V_{IN} = 3.0 V, V_{OUT} = 1.5 V, I_{OUT} = 50 mA.
10. Guaranteed by design and characterization.
11. Performance guaranteed over the indicated operating temperature range by design and/or characterization production tested at T_J = T_A = 25°C. Low duty cycle pulse techniques are used during testing to maintain the junction temperature as close to ambient as possible. 12. Respect SOA.

ELECTRICAL CHARACTERISTICS – Voltage Version 1.8 V

 $-40^{\circ}C \le T_J \le 125^{\circ}C$; $V_{IN} = 2.8V$; $I_{OUT} = 1 \text{ mA}$, $C_{IN} = C_{OUT} = 1.0 \ \mu\text{F}$, unless otherwise noted. Typical values are at $T_J = +25^{\circ}C$. (Note 15)

| Parameter | Test Conditions | | Symbol | Min | Тур | Max | Unit |
|--|---|---------|---------------------|-------|-----|-------|-------------------|
| Operating Input Voltage | lout ≤ 10 mA | | V _{IN} | 2.8 | | 24 | V |
| | 10 mA < I _{OUT} < 50 mA | | | 3.0 | | 24 | 1 |
| Output Voltage Accuracy | 3.0 V < V _{IN} < 24 V, 0 < I _{OUT} < 1 | 0 mA | V _{OUT} | 1.746 | 1.8 | 1.854 | V |
| Line Regulation | $3 \text{ V} \leq \text{Vin} \leq 24 \text{ V}, \text{ I}_{OUT} = 1 \text{ m}$ | A | Reg _{LINE} | | 2 | 10 | mV |
| Load Regulation | I _{OUT} = 0 mA to 50 mA | | Reg _{LOAD} | | 5 | 10 | mV |
| Dropout Voltage (Note 13) | | | V _{DO} | | | | mV |
| Maximum Output Current | (Note 16) | | I _{OUT} | 100 | | 200 | mA |
| Ground Current | 0 < I _{OUT} < 50 mA, V _{IN} = 24 | V | I _{GND} | | 3.4 | 5.8 | μA |
| Power Supply Rejection Ratio | $ \begin{array}{c} V_{IN} = 3.0 \ V, \ V_{OUT} = 1.8 \ V \\ V_{PP} = 200 \ mV \ modulation \\ I_{OUT} = 1 \ mA, \ C_{OUT} = 10 \ \mu F \end{array} f = 1 \ \ \ \ \ \ \ \ \ \ \ \ \$ | 100 kHz | PSRR | | 60 | | dB |
| Output Noise Voltage | Vout = 1.8 V, lout = 50 mA f = 200 Hz to 100 kHz, C _{OUT} = | | V _N | | 95 | | μV _{rms} |
| Thermal Shutdown Temperature (Note 14) | Temperature increasing from TJ = | +25°C | T _{SD} | | 170 | | °C |
| Thermal Shutdown Hysteresis (Note 14) | Temperature falling from T _S | D | T _{SDH} | - | 15 | - | °C |

13. Not characterized at $V_{IN} = 3.0 \text{ V}$, $V_{OUT} = 1.8 \text{ V}$, $I_{OUT} = 50 \text{ mA}$ 14. Guaranteed by design and characterization. 15. Performance guaranteed over the indicated operating temperature range by design and/or characterization production tested at $T_J = T_A = 25^{\circ}$ C. Low duty cycle pulse techniques are used during testing to maintain the junction temperature as close to ambient as possible. 16. Respect SOA.

ELECTRICAL CHARACTERISTICS – Voltage Version 2.1 V

 $-40^{\circ}C \le T_J \le 125^{\circ}C$; $V_{IN} = 3.1V$; $I_{OUT} = 1$ mA, $C_{IN} = C_{OUT} = 1.0 \ \mu$ F, unless otherwise noted. Typical values are at $T_J = +25^{\circ}C$. (Note 19)

| Parameter | Test Conditions | | Symbol | Min | Тур | Max | Unit |
|---|---|---|---------------------|-------|-----|-------|---------------|
| | | | | | 19P | | |
| Operating Input Voltage | 0 < I _{OUT} < 50 mA | | V _{IN} | 3.1 | | 24 | V |
| Output Voltage Accuracy | 3.1 V < V _{IN} < 24 V, 0 < I _{OUT} · | < 50 mA | V _{OUT} | 2.058 | 2.1 | 2.142 | V |
| Line Regulation | $3.1 \text{ V} \le \text{Vin} \le 24 \text{ V}, \text{ I}_{OUT} = 1 \text{ mA}$ | | Reg _{LINE} | | 3 | 45 | mV |
| | 3.3 V \leq VIN \leq 24 V, I _{OUT} = | 1 mA | | | 3 | 10 | |
| Load Regulation | I _{OUT} = 0 mA to 50 mA | Ą | Reg _{LOAD} | | 10 | 15 | mV |
| Dropout Voltage (Note 17) | | | V _{DO} | | | | mV |
| Maximum Output Current | (Note 20) | | I _{OUT} | 100 | | 200 | mA |
| Ground Current | 0 < I _{OUT} < 50 mA, V _{IN} = 2 | 24 V | I _{GND} | | 3.4 | 5.8 | μA |
| Power Supply Rejection Ratio | $\label{eq:VIN} \begin{array}{l} V_{IN} = 3.1 \text{ V}, V_{OUT} = 2.1 \text{ V} \\ V_{PP} = 200 \text{ mV} \text{ modulation} \\ I_{OUT} = 1 \text{ mA}, C_{OUT} = 10 \mu\text{F} \end{array}$ | = 100 kHz | PSRR | | 60 | | dB |
| Output Noise Voltage | | Voυτ = 2.1 V, loυτ = 50 mA f = 200 Hz to 100 kHz, C _{OUT} = 10 μF | | | 105 | | μV_{rms} |
| Thermal Shutdown Temperature (Note 18) | Temperature increasing from $T_J = +25^{\circ}C$ | | T _{SD} | | 170 | | °C |
| Thermal Shutdown Hysteresis (Note 18) | Temperature falling from | T _{SD} | T _{SDH} | - | 15 | - | °C |

17. Not characterized at $V_{IN} = 3.1 \text{ V}$, $V_{OUT} = 2.1 \text{ V}$, $I_{OUT} = 50 \text{ mA}$ 18. Guaranteed by design and characterization. 19. Performance guaranteed over the indicated operating temperature range by design and/or characterization production tested at $T_J = T_A = 25^{\circ}$ C. Low duty cycle pulse techniques are used during testing to maintain the junction temperature as close to ambient as possible. 20. Respect SOA.

ELECTRICAL CHARACTERISTICS – Voltage Version 2.5 V

 $-40^{\circ}C \le T_J \le 125^{\circ}C$; $V_{IN} = 3.5 \text{ V}$; $I_{OUT} = 1 \text{ mA}$, $C_{IN} = C_{OUT} = 1.0 \ \mu\text{F}$, unless otherwise noted. Typical values are at $T_J = +25^{\circ}C$. (Note 23)

| | | | | | | , |
|---|--|---------------------|------|-----|------|-------------------|
| Parameter | Test Conditions | Symbol | Min | Тур | Max | Unit |
| Operating Input Voltage | 0 < I _{OUT} < 50 mA | V _{IN} | 3.5 | | 24 | V |
| Output Voltage Accuracy | 3.5 V < V _{IN} < 24 V, 0 < I _{OUT} < 50 mA | V _{OUT} | 2.45 | 2.5 | 2.55 | V |
| Line Regulation | V_{OUT} + 1 V \leq V _{IN} \leq 24 V, I _{OUT} = 1 mA | Reg _{LINE} | | 3 | 10 | mV |
| Load Regulation | I _{OUT} = 0 mA to 50 mA | Reg _{LOAD} | | 10 | 15 | mV |
| Dropout Voltage (Note 21) | $V_{DO} = V_{IN} - (V_{OUT(NOM)} - 125 \text{ mV})$ $I_{OUT} = 50 \text{ mA}$ | V _{DO} | | 260 | 450 | mV |
| Maximum Output Current | (Note 24) | I _{OUT} | 100 | | 200 | mA |
| Ground Current | 0 < I _{OUT} < 50 mA, VIN = 24 V | I _{GND} | | 3.4 | 5.8 | μA |
| Power Supply Rejection Ratio | $V_{\text{IN}} = 3.5 \text{ V}, V_{\text{OUT}} = 2.5 \text{ V}$ $V_{\text{PP}} = 200 \text{ mV modulation}$ $I_{\text{OUT}} = 1 \text{ mA}, C_{\text{OUT}} = 10 \mu\text{F}$ | Hz PSRR | | 60 | | dB |
| Output Noise Voltage | V_{OUT} = 2.5 V, I_{OUT} = 50 mA f = 200 Hz to 100 kHz, C_{OUT} = 10 μF | V _N | | 115 | | μV _{rms} |
| Thermal Shutdown Temperature (Note 22) | Temperature increasing from $T_J = +25^{\circ}$ | C T _{SD} | | 170 | | °C |
| Thermal Shutdown Hysteresis (Note 22) | Temperature falling from T _{SD} | T _{SDH} | - | 15 | - | °C |

21. Characterized when V_{OUT} falls 125 mV below the regulated voltage and only for devices with V_{OUT} = 2.5 V. 22. Guaranteed by design and characterization. 23. Performance guaranteed over the indicated operating temperature range by design and/or characterization production tested at $T_J = T_A = 25^{\circ}$ C. Low duty cycle pulse techniques are used during testing to maintain the junction temperature as close to ambient as possible. 24. Respect SOA.

ELECTRICAL CHARACTERISTICS – Voltage Version 3.0 V

 $-40^{\circ}C \le T_J \le 125^{\circ}C$; $V_{IN} = 4.0 \text{ V}$; $I_{OUT} = 1 \text{ mA}$, $C_{IN} = C_{OUT} = 1.0 \mu$ F, unless otherwise noted. Typical values are at $T_J = +25^{\circ}C$. (Note 27)

| | | • • | | | | , |
|---|--|------------------------|------|-----|------|-------------------|
| Parameter | Test Conditions | Symbol | Min | Тур | Max | Unit |
| Operating Input Voltage | 0 < I _{OUT} < 50 mA | Vin | 4.0 | | 24 | V |
| Output Voltage Accuracy | 4.0 V < V _{IN} < 24 V, 0< I _{OUT} < 50 m | A Vout | 2.94 | 3.0 | 3.06 | V |
| Line Regulation | V_{OUT} + 1 V \leq V _{IN} \leq 24 V, I _{OUT} = 1 m | nA Reg _{LINE} | | 3 | 10 | mV |
| Load Regulation | I _{OUT} = 0 mA to 50 mA | Reg _{LOAD} | | 10 | 15 | mV |
| Dropout voltage (Note 25) | $V_{DO} = V_{IN} - (V_{OUT(NOM)} - 150 \text{ mV})$ $I_{OUT} = 50 \text{ mA}$ | /) Vdo | | 250 | 400 | mV |
| Maximum Output Current | (Note 28) | Ιουτ | 100 | | 200 | mA |
| Ground current | 0 < IOUT < 50 mA, VIN = 24 V | Ignd | | 3.4 | 5.8 | μA |
| Power Supply Rejection Ratio | $ \begin{array}{c} V_{IN} = 4.0 \ V, \ V_{OUT} = 3.0 \ V \\ V_{PP} = 100 \ mV \ modulation \\ I_{OUT} = 1 \ mA, \ C_{OUT} = 10 \ \mu F \end{array} f = 100 \label{eq:VIN} $ | kHz PSRR | | 60 | | dB |
| Output Noise Voltage | V _{OUT} = 3 V, I _{OUT} = 50 mA, f = 200 Hz to 100 kHz, C _{OUT} = 10 µ | ιF | | 135 | | μV _{rms} |
| Thermal Shutdown Temperature (Note 26) | Temperature increasing from $T_J = +2$ | 5°C Tsd | | 170 | | °C |
| Thermal Shutdown Hysteresis (Note 26) | Temperature falling from T _{SD} | Tsdh | - | 25 | - | °C |

25. Characterized when VOUT falls 150 mV below the regulated voltage and only for devices with VOUT = 3.0 V

26. Guaranteed by design and characterization.

27. Performance guaranteed over the indicated operating temperature range by design and/or characterization production tested

at $T_J = T_A = 25^{\circ}$ C. Low duty cycle pulse techniques are used during testing to maintain the junction temperature as close to ambient as possible.

28. Respect SOA

ELECTRICAL CHARACTERISTICS – Voltage Version 3.3 V

 $-40^{\circ}C \le T_J \le 125^{\circ}C$; $V_{IN} = 4.3 \text{ V}$; $I_{OUT} = 1 \text{ mA}$, $C_{IN} = C_{OUT} = 1.0 \mu$ F, unless otherwise noted. Typical values are at $T_J = +25^{\circ}C$. (Note 31)

| | | | | | | , |
|--|---|---------------------|-------|-----|-------|---------------|
| Parameter | Test Conditions | Symbol | Min | Тур | Max | Unit |
| Operating Input Voltage | 0 < I _{OUT} < 50 mA | V _{IN} | 4.3 | | 24 | V |
| Output Voltage Accuracy | 4.3 V < V _{IN} < 24 V, 0 < I _{OUT} < 50 mA | V _{OUT} | 3.234 | 3.3 | 3.366 | V |
| Line Regulation | V_{OUT} + 1 V \leq VIN \leq 24 V, I _{OUT} = 1 mA | Reg _{LINE} | | 3 | 10 | mV |
| Load Regulation | I _{OUT} = 0 mA to 50 mA | Reg _{LOAD} | | 10 | 15 | mV |
| Dropout Voltage (Note 29) | $V_{DO} = V_{IN} - (V_{OUT(NOM)} - 165 \text{ mV})$ $I_{OUT} = 50 \text{ mA}$ | V _{DO} | | 230 | 350 | mV |
| Maximum Output Current | (Note 32) | I _{OUT} | 100 | | 200 | mA |
| Ground Current | 0 < IOUT < 50 mA, VIN = 24 V | I _{GND} | | 3.4 | 5.8 | μΑ |
| Power Supply Rejection Ratio | $ \begin{array}{c} V_{IN} = 4.3 \text{ V}, V_{OUT} = 3.3 \text{ V} \\ V_{PP} = 200 \text{ mV modulation} \\ I_{OUT} = 1 \text{ mA}, C_{OUT} = 10 \ \mu\text{F} \end{array} \right f = 100 \ \text{k} $ | Hz PSRR | | 60 | | dB |
| Output Noise Voltage | Vout = 4.3 V, lout = 50 mA f = 200 Hz to 100 kHz, C _{OUT} = 10 μF | V _N | | 140 | | μV_{rms} |
| Thermal Shutdown Temperature (Note 30) | Temperature increasing from T _J = +25° | C T _{SD} | | 170 | | °C |
| Thermal Shutdown Hysteresis (Note 30) | Temperature falling from T _{SD} | T _{SDH} | _ | 15 | - | °C |

29. Characterized when VOUT falls 165 mV below the regulated voltage and only for devices with VOUT = 3.3 V.

30. Guaranteed by design and characterization.

31. Performance guaranteed over the indicated operating temperature range by design and/or characterization production tested at T_J = T_A = 25°C. Low duty cycle pulse techniques are used during testing to maintain the junction temperature as close to ambient as possible.
32. Respect SOA.

ELECTRICAL CHARACTERISTICS – Voltage Version 5.0 V

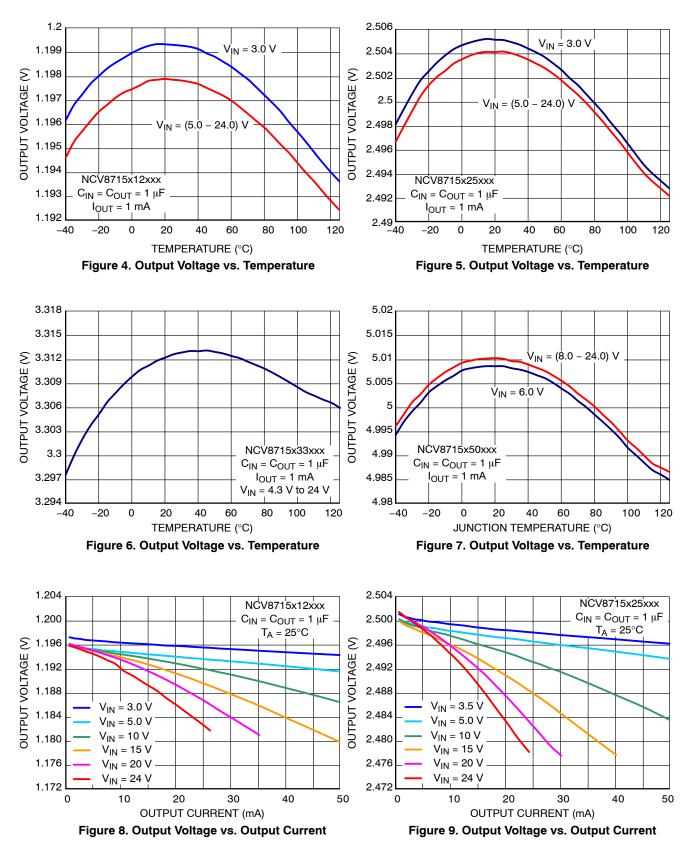
 $-40^{\circ}C \le T_J \le 125^{\circ}C$; $V_{IN} = 6.0 \text{ V}$; $I_{OUT} = 1 \text{ mA}$, $C_{IN} = C_{OUT} = 1 \mu$ F, unless otherwise noted. Typical values are at $T_J = +25^{\circ}C$. (Note 35)

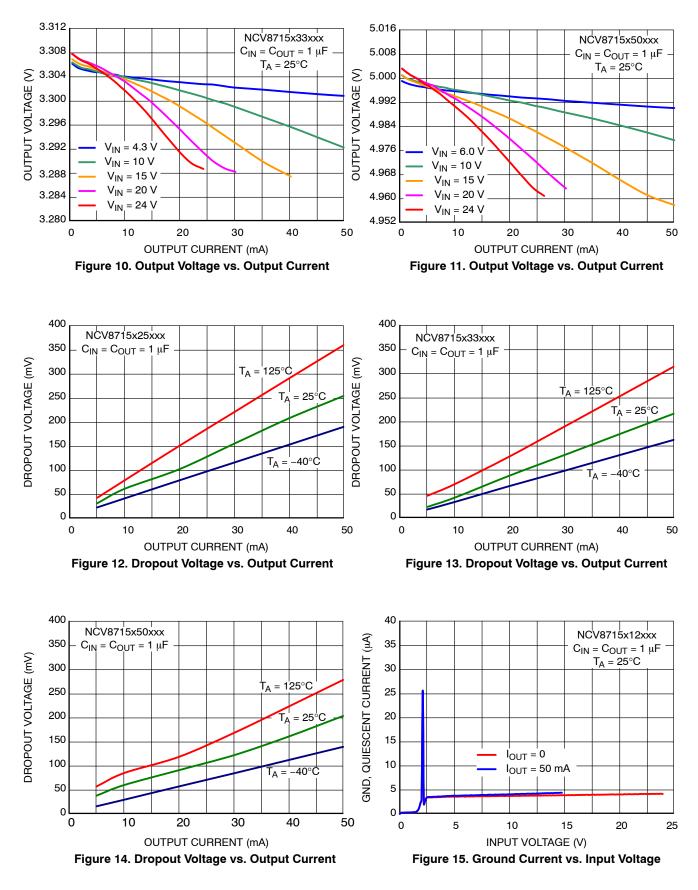
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|---|---|------------------|---------------------|-----|-----|-----|-------------------|--|
| Parameter | Test Conditions | | Symbol | Min | Тур | Max | Unit | |
| Operating Input Voltage | 0 < Iout < 50 mA | 0 < IOUT < 50 mA | | 6.0 | | 24 | V | |
| Output Voltage Accuracy | 6.0V < VIN < 24V, 0< IOUT < | 50 mA | V _{OUT} | 4.9 | 5.0 | 5.1 | V | |
| Line Regulation | Vout + 1 V \leq Vin \leq 24 V, lout | t = 1mA | Reg _{LINE} | | 3 | 10 | mV | |
| Load Regulation | IOUT = 0 mA to 50 mA | ł | Reg _{LOAD} | | 10 | 20 | mV | |
| Dropout Voltage (Note 33) | $V_{DO} = V_{IN} - (V_{OUT(NOM)} - 250 \text{ mV})$ $I_{OUT} = 50 \text{ mA}$ | | V _{DO} | | 230 | 350 | mV | |
| Maximum Output Current | (Note 36) | | I _{OUT} | 90 | | 200 | mA | |
| Ground Current | 0 < IOUT < 50 mA, VIN = 2 | 24 V | I _{GND} | | 3.4 | 5.8 | μA | |
| Power Supply Rejection Ratio | | = 100 kHz | PSRR | | 56 | | dB | |
| Output Noise Voltage | Vout = 5.0 V, lout = 50 f = 200 Hz to 100 kHz, C _{OUT} | | V _N | | 190 | | μV _{rms} | |
| Thermal Shutdown Temperature (Note 34) | Temperature increasing from $T_J = +25^{\circ}C$ | | T _{SD} | | 170 | | °C | |
| Thermal Shutdown Hysteresis (Note 34) | Temperature falling from | T _{SD} | T _{SDH} | - | 15 | _ | °C | |

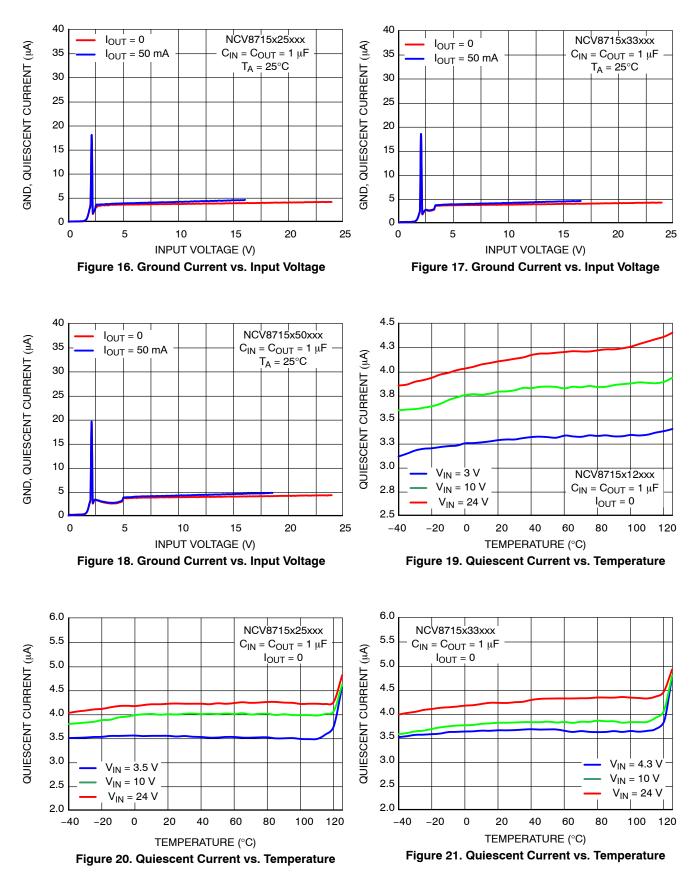
33. Characterized when VOUT falls 250 mV below the regulated voltage and only for devices with VOUT = 5.0 V.

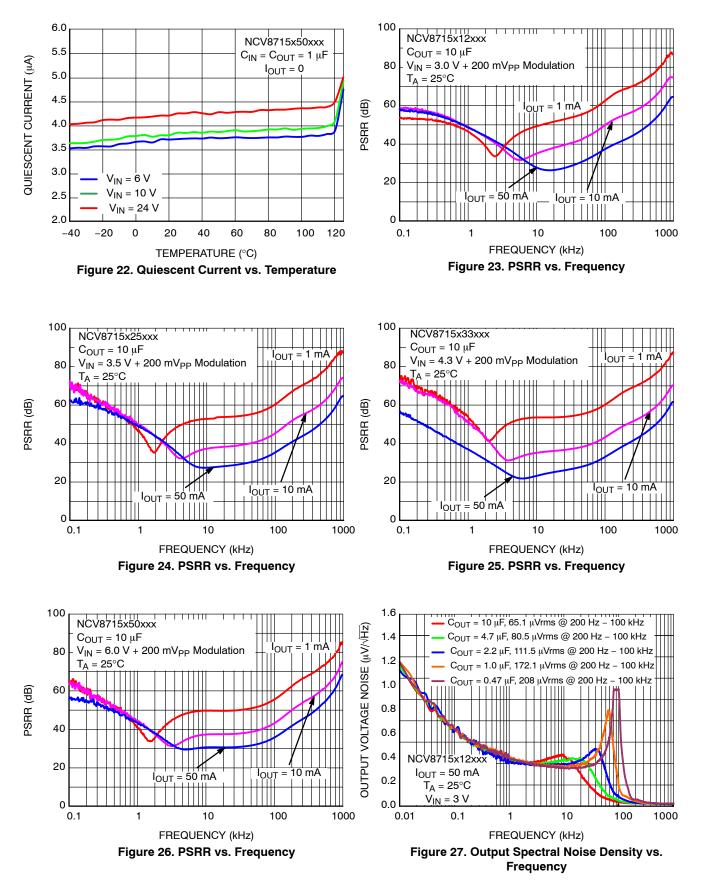
34. Guaranteed by design and characterization.

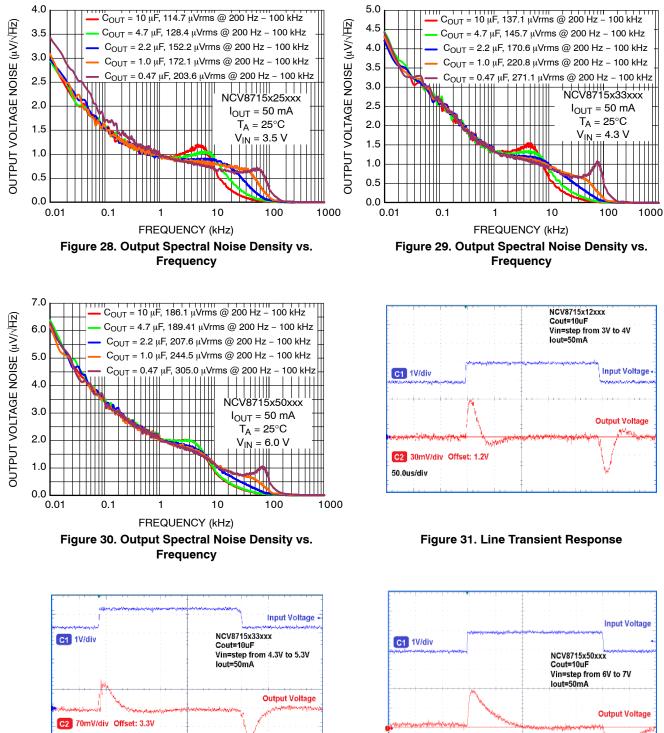
35. Performance guaranteed over the indicated operating temperature range by design and/or characterization production tested at T_J = T_A = 25°C. Low duty cycle pulse techniques are used during testing to maintain the junction temperature as close to ambient as possible.
36. Respect SOA.











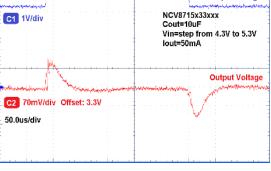


Figure 32. Line Transient Response

Figure 33. Line Transient Response

C2 60mV/div Offset: 5.0V

50.0us/div

| C2 100mV/div Offset: 1.2V | Output Voltage |
|---------------------------|--|
| | NCV8715x12xxx Vin=3V Cout=10µF lout=step from 1mA to 50mA |
| C4 50mA/div | Output Current |

Figure 34. Load Transient Response

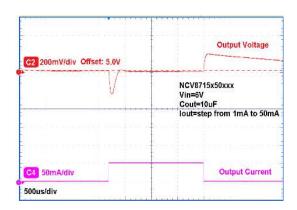


Figure 36. Load Transient Response

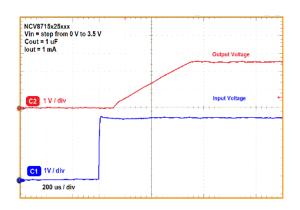


Figure 38. Input Voltage Turn-On Response

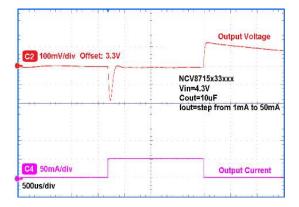


Figure 35. Load Transient Response

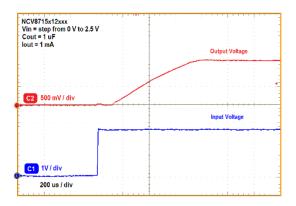


Figure 37. Input Voltage Turn-On Response

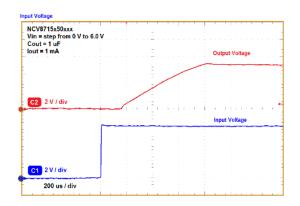


Figure 39. Input Voltage Turn-On Response

APPLICATIONS INFORMATION

The NCV8715 is the member of new family of Wide Input Voltage Range Low Dropout Regulators which delivers Ultra Low Ground Current consumption, Good Noise and Power Supply Rejection Ratio Performance.

Input Decoupling (CIN)

It is recommended to connect at least 0.1 μ F Ceramic X5R or X7R capacitor between IN and GND pin of the device. This capacitor will provide a low impedance path for any unwanted AC signals or Noise superimposed onto constant Input Voltage. The good input capacitor will limit the influence of input trace inductances and source resistance during sudden load current changes.

Higher capacitance and lower ESR Capacitors will improve the overall line transient response.

Output Decoupling (COUT)

The NCV8715 does not require a minimum Equivalent Series Resistance (ESR) for the output capacitor. The device is designed to be stable with standard ceramics capacitors with values of $0.47 \,\mu\text{F}$ or greater up to $10 \,\mu\text{F}$. The X5R and X7R types have the lowest capacitance variations over temperature thus they are recommended.

Power Dissipation and Heat sinking

The maximum power dissipation supported by the device is dependent upon board design and layout. Mounting pad configuration on the PCB, the board material, and the ambient temperature affect the rate of junction temperature rise for the part. The maximum power dissipation the NCV8715 can handle is given by:

$$\mathsf{P}_{\mathsf{D}(\mathsf{MAX})} = \frac{\left[\mathsf{T}_{\mathsf{J}(\mathsf{MAX})} - \mathsf{T}_{\mathsf{A}}\right]}{\mathsf{R}_{\theta\mathsf{J}\mathsf{A}}} \tag{eq. 1}$$

The power dissipated by the NCV8715 for given application conditions can be calculated from the following equations:

$$\mathsf{P}_\mathsf{D} \approx \mathsf{V}_\mathsf{IN} \Big(\mathsf{I}_\mathsf{GND} \big(\mathsf{I}_\mathsf{OUT} \big) \Big) + \mathsf{I}_\mathsf{OUT} \Big(\mathsf{V}_\mathsf{IN} - \mathsf{V}_\mathsf{OUT} \Big) \ \text{(eq. 2)}$$

or

$$V_{\text{IN(MAX)}} \approx \frac{\mathsf{P}_{\text{D(MAX)}} + \left(V_{\text{OUT}} \times I_{\text{OUT}} \right)}{I_{\text{OUT}} + I_{\text{GND}}} \qquad (\text{eq. 3})$$

For reliable operation, junction temperature should be limited to $+125^{\circ}$ C maximum.

Hints

VIN and GND printed circuit board traces should be as wide as possible. When the impedance of these traces is high, there is a chance to pick up noise or cause the regulator to malfunction. Place external components, especially the output capacitor, as close as possible to the NCV8715, and make traces as short as possible.

ORDERING INFORMATION

| Device | Nominal Output Voltage | Marking | Package | Shipping [†] | |
|--------------------------|---------------------------|---------|----------------------------|---|--|
| NCV8715SQ12T2G | 1.2 V | V5A | | | |
| NCV8715SQ15T2G | 1.5 V | V5C | | | |
| NCV8715SQ18T2G | 1.8 V | V5D | SC-88A/SC-70 (Pb-Free)* | 3000 / Tape & Reel | |
| NCV8715SQ21T2G | 2.1 V | V5J | | | |
| NCV8715SQ25T2G | 2.5 V | V5E | | | |
| NCV8715SQ30T2G | 3.0 V | V5F | | | |
| NCV8715SQ33T2G | 3.3 V | V5G | | | |
| NCV8715SQ50T2G | 5.0 V | V5H | | | |
| NCV8715MX12TBG | 1.2 V | VA | | 3000 or 5000 / Tape & Reel (Note 37) | |
| NCV8715MX15TBG | 1.5 V | VC | XDFN6 (Pb-Free)* | | |
| NCV8715MX18TBG (Note 37) | 1.8 V | VE | | | |
| NCV8715MX25TBG | 2.5 V | VE | | | |
| NCV8715MX30TBG (Note 37) | 3.0 V | VF | (1.5.1.00) | | |
| NCV8715MX33TBG (Note 37) | 3.3 V | VG | | | |
| NCV8715MX50TBG (Note 37) | 5.0 V | VH | | | |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
 *For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques

Reference Manual, SOLDERRM/D.

37. Products processed after October 1, 2022 are shipped with quantity 5000 units / tape & reel.

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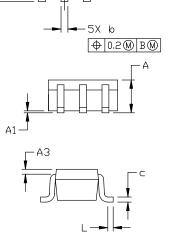


SCALE 2:1

SC-88A (SC-70-5/SOT-353) CASE 419A-02 ISSUE M

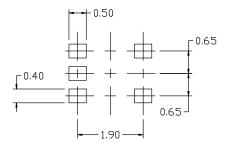
NDTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. 419A-01 DBSDLETE. NEW STANDARD 419A-02
- 4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.1016MM PER SIDE.



e

F1



RECOMMENDED MOUNTING FOOTPRINT

For additional information on our
 Pb-Free strategy and soldering details,
 please download the DN Semiconductor
 Soldering and Mounting Techniques
 Reference Manual, SDLDERRM/D.

| DIM | MILLIMETERS | | | |
|-------|----------------|------|------|--|
| ויודע | MIN. | NDM. | MAX, | |
| А | 0.80 | 0.95 | 1.10 | |
| A1 | O | | 0.10 | |
| A3 | 0.20 REF | | | |
| b | 0.10 | 0.20 | 0.30 | |
| С | 0.10 | | 0,25 | |
| D | 1.80 | 2.00 | 5,20 | |
| E | 2.00 | 2.10 | 5,20 | |
| E1 | 1.15 | 1.25 | 1.35 | |
| e | 0.65 BSC | | | |
| L | 0.10 0.15 0.30 | | | |

GENERIC MARKING





*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

| PIN 1. BASE PIN 1. ANODE PIN 1. ANODE 1 PIN 1. SOURCE 1 PIN 1. CATHODE 2. EMITTER 2. EMITTER 2. N/C 2. DRAIN 1/2 2. COMMON ANODE 3. BASE 3. BASE 3. ANODE 2 3. SOURCE 1 3. CATHODE 2 4. COLLECTOR 4. COLLECTOR 4. CATHODE 2 4. GATE 1 4. CATHODE 3 5. COLLECTOR 5. CATHODE 5. CATHODE 1 5. GATE 2 5. CATHODE 4 STYLE 6: STYLE 7: STYLE 8: STYLE 9: Note: Please refer to datasheet for style callout. If style type is not callout. If style type is not callout. If style type is not callout. Collector 3. EMITTER 1 3. BASE 3. N/C 3. ANODE 2 0. attinut the datasheet refer to the callout. If style type is not callout. If style type is not callout. Collector 4. COLLECTOR 2/BASE 1 5. COLLECTOR 4. BASE 4. ANODE out in the datasheet refer to the callout. If style type is not callout. Collector 5. COLLECTOR 2/BASE 1 5. COLLECTOR 5. EMITTER 5. ANODE out in the datasheet refer to the callout. If style type is not callout. Collector 6. COLLECTOR 2/BASE 1 5. COLLECTOR 5. EMITTER 5. ANODE datasheet pinout or pin assignment DOCUMENT NUMBER: 98ASB42984B | DESCRIPTION: | SC-88A (SC-70- | 5/SOT-353) | | | PAGE 1 OF 1 |
|---|---|---|--|---|--|--|
| 2. EMITTER 2. EMITTER 2. N/C 2. DRAIN 1/2 2. COMMON ANODE 3. BASE 3. BASE 3. ANODE 2 3. SOURCE 1 3. CATHODE 2 4. COLLECTOR 4. COLLECTOR 4. CATHODE 2 4. GATE 1 4. CATHODE 3 5. COLLECTOR 5. CATHODE 5. CATHODE 1 5. GATE 2 5. CATHODE 4 STYLE 6: STYLE 7: STYLE 8: STYLE 9: Note: Please refer to datasheet for PIN 1. EMITTER 2 2. BASE 2 2. EMITTER 2. COLLECTOR 2. CATHODE 3. EMITTER 1 3. BASE 3. N/C 3. ANODE out in the datasheet refer to the cout in the datas | DOCUMENT NUMBER: | 98ASB42984B | | | | |
| 2. EMITTER 2. EMITTER 2. N/C 2. DRAIN 1/2 2. COMMON ANODE 3. BASE 3. BASE 3. ANODE 2 3. SOURCE 1 3. CATHODE 2 4. COLLECTOR 4. COLLECTOR 4. CATHODE 2 4. GATE 1 4. CATHODE 3 | PIN 1. EMITTER 2 2. BASE 2 3. EMITTER 1 4. COLLECTOR | PIN 1. BASE 2. EMITTER 3. BASE 4. COLLECTOR | PIN 1. CATHODE 2. COLLECTOR 3. N/C 4. BASE | PIN 1. ANODE 2. CATHODE 3. ANODE 4. ANODE | style callout. If style t out in the datasheet i | ype is not called refer to the device |
| STYLE 1: STYLE 2: STYLE 3: STYLE 4: STYLE 5: | PIN 1. BASE 2. EMITTER 3. BASE 4. COLLECTOR | PIN 1. ANODE 2. EMITTER 3. BASE 4. COLLECTOR | PIN 1. ANODE 1 2. N/C 3. ANODE 2 4. CATHODE 2 | PIN 1. SOURCE 1 2. DRAIN 1/2 3. SOURCE 1 4. GATE 1 | PIN 1. CATHODE 2. COMMON ANOE 3. CATHODE 2 4. CATHODE 3 | DE |

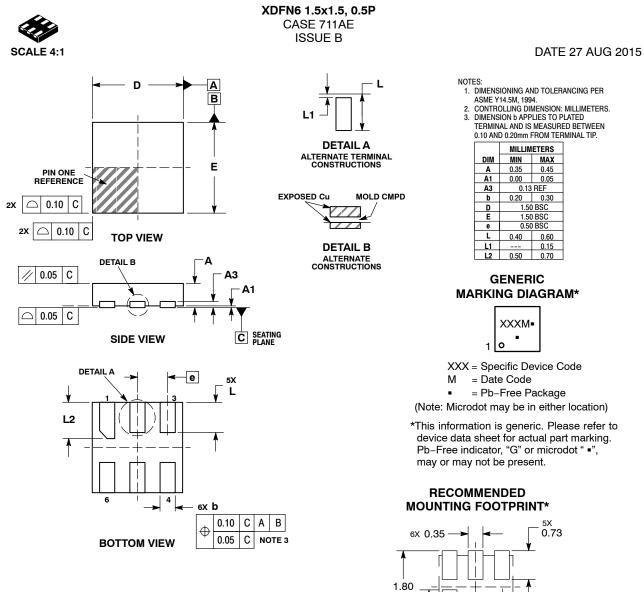
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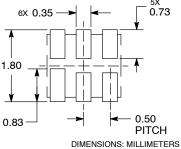
XXX = Specific Device Code

M = Date Code = Pb-Free Package

⁽Note: Microdot may be in either location)







*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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| DESCRIPTION: | XDFN6, 1.5 X 1.5, 0.5 P | | PAGE 1 OF 1 | | |
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